



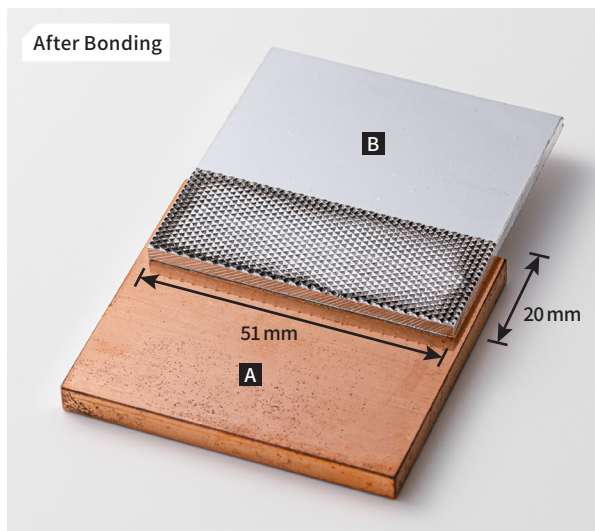
Patented

Application

Bonding

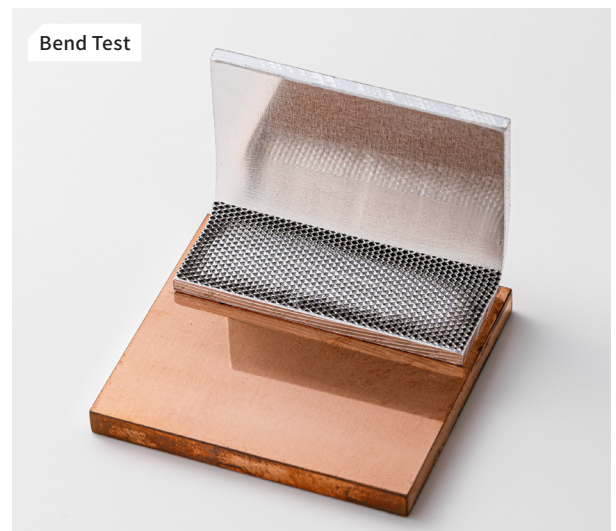
Aluminium and Copper Bonded over Large Area

Over 1,000 mm² Bonding Area with our 10 kW Double Power System



A Copper (55x50 mm; t=5 mm)

B Aluminium (51x51 mm; t=3 mm)



Pull Test

Bond strength: 14.6 kN

Electrical Contact Resistance: 0.567 $\mu\Omega$

(Measured by Hitachi, Ltd.)

Double Power System

With probes on both sides of the horn, this system delivers up to 10 kW, twice the output of a standard MZ system. A breakthrough in bonding technology.

Key Points

- ✓ Clean metal-to-metal bonding
- ✓ No adhesives required
- ✓ Bonding at room-temperature and under atmospheric conditions
- ✓ Alloy Bonding
- ✓ Process time approx. 3~5 s
- ✓ No part damage or oxidization
- ✓ Minimal anvil and tool heating

System Used

- ✓ Double Power System (15MZs)



AP-E-0077A4-2026070601